CLAIMS

What is claimed is:

1. A mounting bracket for a device comprising:

a deforming element configured from a resiliently-deformable surface, wherein said deforming element increases a deformability of said resiliently-deformable surface; and

a pair of attachment members disposed on opposite sides of and attached to said surface and adapted to interface with the device upon deformation of said deforming element.

2. The mounting bracket according to claim 1 wherein said each of said attachment members comprises fastener attachment sites for receiving fasteners for interfacing said attachment members with the device upon deformation of said deforming element.

3. The mounting bracket according to claim 1 wherein said deforming element comprises one or more compression elements.

4. The mounting bracket according to claim 1 wherein said deforming element comprises a serpentine metal strip.

5. The mounting bracket according to claim 1 wherein said deforming element comprises a portion of said surface adapted to provide a spring element.

6. The mounting bracket according to claim 1 wherein said deforming element is adapted to provide linear deformation of said surface.

7. The mounting bracket according to claim 1 wherein said deforming element of said surface is compressed to bring said attachment members into contact with said device.

8. The mounting bracket according to claim 1 wherein said deforming element is comprised of machined aluminum alloy.

9. The mounting bracket according to claim 1 wherein said attachment members are comprised of aluminum alloy.

10. The mounting bracket according to claim 1 further comprising:

a thermal interface material disposed between said attachment members and said device.

11. The mounting bracket according to claim 10 wherein said thermal interface material is a thermally-conductive elastomer sheet material.

13. The mounting bracket according to claim 1 wherein said device is a computer storage device.

14. The mounting bracket according to claim 1 further comprising screw holes defined in said attachment members.

15. The mounting bracket according to claim 14 wherein said resiliently-deformable surface is deformed by action of screws inserted through said screw holes into said device.

16. The mounting bracket according to claim 1 wherein said resiliently-deformable surface comprises a compressible lateral midline portion connecting opposing outer lateral portions of said surface.

17. The mounting bracket according to claim 1 wherein said resiliently-deformable surface includes a flat spring midline portion connecting opposing outer lateral portions of said surface.

18. A method for dissipating heat in an electronic device comprising:

positioning said electronic device onto a bracket made from thermally conductive material;

influencing said bracket to increase a contact area between said electronic device and attachment members of said bracket; and

fastening said electronic device to said attachment members to create a thermal contact between said electronic device and said attachment members.

19. The method of claim 18 wherein said bracket is constructed from aluminum alloy.

20. The method of claim 18 further comprising:

disposing a thermal interface material between said electronic device and said attachment members.

21. The method of claim 20 wherein said thermal interface material comprises a thermally-conductive elastomer sheet material.

22. A system for dissipating heat in a computer-mounted device comprising:

a mounting bracket constructed from a thermal conductor;

sidewalls on said mounting bracket constructed from said thermal conductor;

fastening receptacles within said sidewalls for securing said computer-mounted device in relation to a computer, wherein said fastening creates a thermal interface between said computer-mounted device and said sidewalls.

23. The system of claim 22 further comprising a conduction layer disposed on said sidewalls, wherein said conduction layer is disposed between said sidewalls and said computer-mounted device when said device is fastened to said sidewalls.

24. The system of claim 23 wherein said conduction layer comprises a thermally-conductive elastomer sheet.

25. The system of claim 22 wherein said thermal conductor comprises aluminum alloy.